



# CMS80F752x Datasheet

**Enhanced Flash 8-Bit 1T 8051 Microcontrollers**

**Rev. 0.5.2**

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# 1. Product Features

## 1.1 Features

- ◆ **Compatible with MCS-51 1T Instruction Set**
  - System clock frequency supports up to 48MHz
  - Fastest machine cycle: 1T<sub>sys</sub> @ F<sub>sys</sub>≤24MHz
  - Fastest machine cycle: 2T<sub>sys</sub> @ F<sub>sys</sub>=48MHz
- ◆ **Memory**
  - Program FLASH: 32K×8Bit
  - Data FLASH: 1K×8Bit
  - Universal RAM: 256×8Bit
  - Universal XRAM: 2K×8Bit
  - Program FLASH supports partition protection and IAP functions
  - Data FLASH supports partition protection
- ◆ **3 Oscillation Modes**
  - HSI-internal high-speed oscillation: 48MHz
  - HSE-external high-speed oscillation: 8MHz/16MHz
  - LSI-internal low-speed oscillation: 32KHz
- ◆ **GPIO**
  - Up to 30 GPIOs
  - Supports pull-up/pull-down resistor function
  - Supports edge (rising edge/falling edge/both edges) interrupt
  - Supports wake-up function
- ◆ **Interrupt Sources**
  - Supports all external port interrupts
  - 4 timer interrupts
  - Other peripheral interrupts
- ◆ **Timers**
  - WDT Timer (Watch Dog Timer)
  - Timer0/1, Timer2
  - Timer5 (supports sleep wake-up function)
  - BRT (serial baud rate clock generator)
- ◆ **Cyclic Redundancy Check Unit**
  - CRC16 (CRC16-CCITT)
- ◆ **Enhanced PWM**
  - 6-channel enhanced PWM
  - 3 independent period counters
  - Supports independent/complementary/synchronous/group modes
  - Supports edge alignment
  - Supports complementary mode dead-time delay function
- ◆ **Communication Modules**
  - 1x SPI
  - 1x I<sup>2</sup>C
  - 2x UART
  - UART1 can be mapped to any GPIO
- ◆ **Operating Voltage Range**
  - 2.5V to 5.5V
- ◆ **Operating Temperature Range**
  - -40°C to 105°C
- ◆ **Low Voltage Reset (LVR)**
  - 2.5V/2.7V/3.0V/3.3V/3.7V/4.0V/4.3V
- ◆ **Low Voltage Detection (LVD)**
  - 2.5V/2.7V/3.0V/3.3V/3.7V/4.0V/4.3V
- ◆ **High-Precision 12-Bit ADC**
  - Up to 30 external AD channels
  - Selectable reference voltage (2.4V/VDD)
- ◆ **Hardware LED Dot Matrix Drive**
  - Fixed clock source
  - Supports cyclic scanning and interrupt scanning
  - Supports selectable data display for each light
  - Supports two selectable conduction times for each light
  - Supports up to 64 LEDs, configurable dot matrix options: 4x4, 5x5, 6x6, 6x7, 7x7, 7x8, 8x8
- ◆ **Hardware LED Matrix Drive**
  - Selectable duty cycle: 1/4, 1/5, 1/6, 1/8
  - Supports both common cathode and common anode modes
  - Supports dimming mode with selectable dimming time
  - Fixed clock source
  - Selectable COM and SEG current
  - Supports up to: 4COM x 26SEG, 5COM x 25SEG, 6COM x 24SEG, 8COM x 22SEG
- ◆ **High Sensitivity Touch**
- ◆ **Low Power Consumption Modes**
  - Idle Mode (IDLE)
  - Sleep Mode (STOP)
- ◆ **Supports 128-Bit Unique ID (UID)**
  - Each chip has a unique ID
- ◆ **Supports Two-wire Serial Programming and Debugging**

## 1.2 Product Comparison

Product model		CMS80F7526	CMS80F7528	CMS80F7529
Peripheral interface				
Maximum clock frequency		48MHz		
Memory module	APROM	32 KB		
	Data FLASH	1 KB		
	RAM	256 B		
	XRAM	2 KB		
Timer	WDT	1		
	Timer0/1	2 (16-bit)		
	Timer2	1 (16-bit)		
	Timer5	1 (16-bit)		
	BRT	1 (10-bit)		
Enhanced digital peripheral	CRC	CRC16-CCITT		
	PWM	6 (16-bit)		
	LED matrix	4COM x 14SEG 5COM x 13SEG 6COM x 12SEG 8COM x 10SEG	4COM x 22SEG 5COM x 21SEG 6COM x 20SEG 8COM x 18SEG	4COM x 26SEG 5COM x 25SEG 6COM x 24SEG 8COM x 22SEG
	LED dot-matrix	4x4、5x5、6x6、6x7、7x7、7x8、8x8		
Communication module	SPI	1		
	I <sup>2</sup> C	1		
	UART	2		
Analog module	12-bit ADC (Number of external channels)	18	26	30
	Touch	18	26	30
GPIO		18	26	30
LVR		2.5V/2.7V/3.0V/3.3V/3.7V/4.0V/4.3V		
LVD		2.5V/2.7V/3.0V/3.3V/3.7V/4.0V/4.3V		
Operating voltage		2.5~5.5V		
Operating temperature		-40~105°C		
Package		SOP20	SOP28	LQFP32

## 2. System Overview

### 2.1 System Introduction

This series features an 8051 core, compatible with the MCS-51 1T instruction system. It is an 8-bit general-purpose I/O chip with a maximum operating frequency of 48MHz. The MCU has the following features:

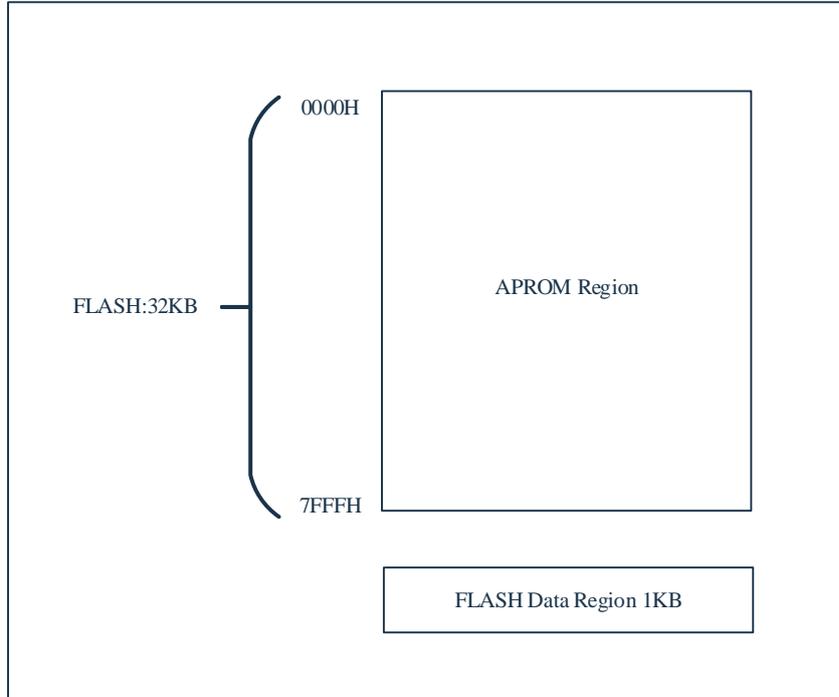
- It has a maximum of 32KB program memory, 256B RAM, 2KB XRAM, and 1KB non-volatile data memory.
- It supports three oscillation modes and external oscillator stop detection.
- It supports three working modes: normal, idle, and sleep, effectively reducing power consumption.
- Built-in low-voltage reset (LVR), low-voltage detection (LVD), and watch dog overflow reset protection features, enhancing system reliability.
- It has multiple interrupt sources, including external interrupts, timer interrupts, and peripheral interrupts, enabling timely response to external events and improving MCU utilization.
- It features six timers that support functions such as timing, counting, input capture, output compare, timer wake-up, and baud rate generation.
- It includes an enhanced PWM and a Cyclic Redundancy Check (CRC) unit.
- It supports up to 8 COM and 26 SEG LED driver modules.
- It offers six 16-bit PWM channels, supporting independent, complementary, and synchronous modes with dead-time control.
- It has one I<sup>2</sup>C, one SPI, and two UART communication modules for data transfer between the system and other devices.
- It includes a high-precision 12-bit ADC with selectable internal reference voltage, up to 30 channels of high-sensitivity touch module, and an integrated temperature sensor, providing richer analog functionalities.

## 2.2 Memory Structure

### 2.2.1 Program Memory FLASH

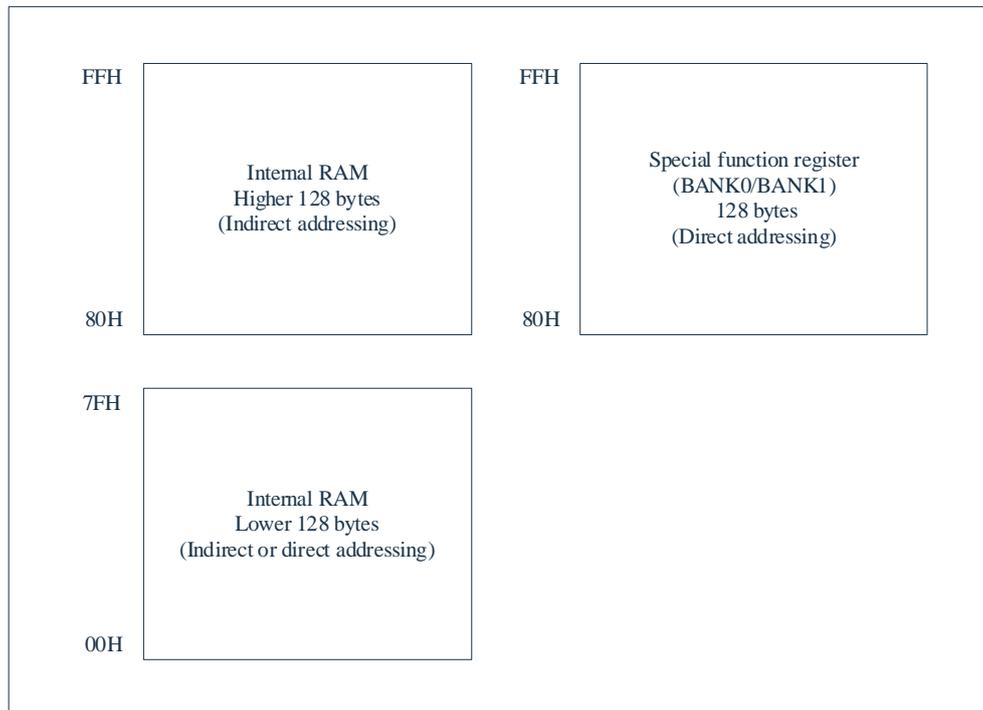
The chip features a 32KB FLASH memory space.

The memory space allocation structure block diagram is as follows:



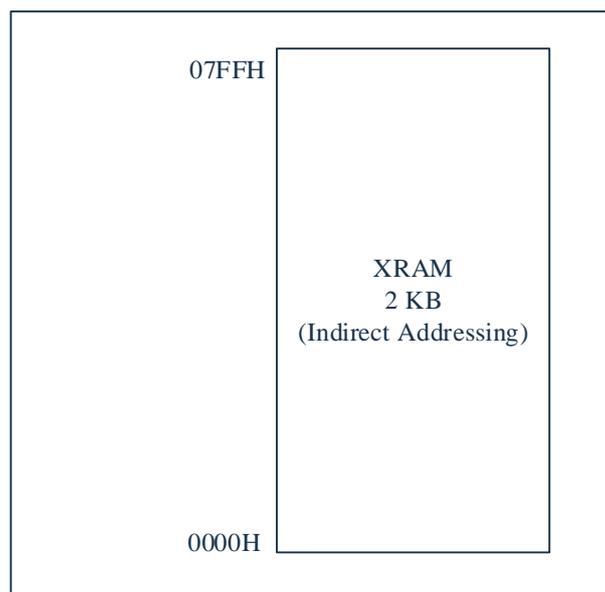
### 2.2.2 Internal Data Memory RAM

The internal data memory is divided into 3 parts: low 128Bytes, high 128Bytes, and SFR. The structure diagram of RAM space allocation is shown in the figure below:



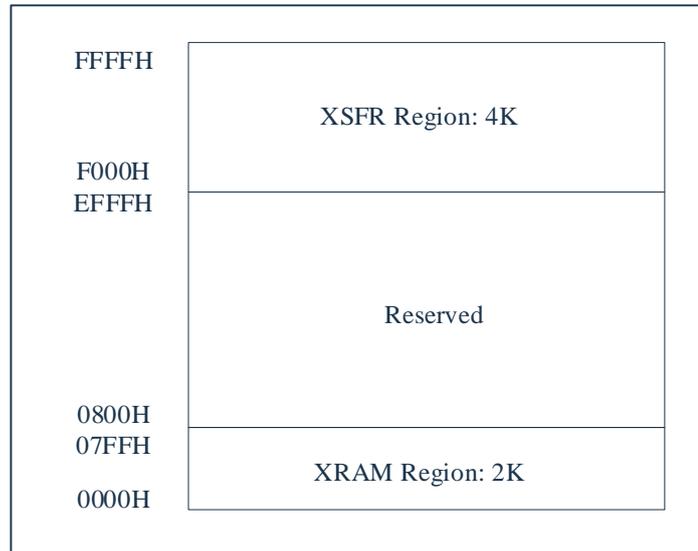
### 2.2.3 External Data Memory XRAM

The chip has a 2KB XRAM area, which is independent of the RAM/FLASH. The XRAM memory space allocation structure block diagram is shown below:



## 2.2.4 Special Function Register XSFR

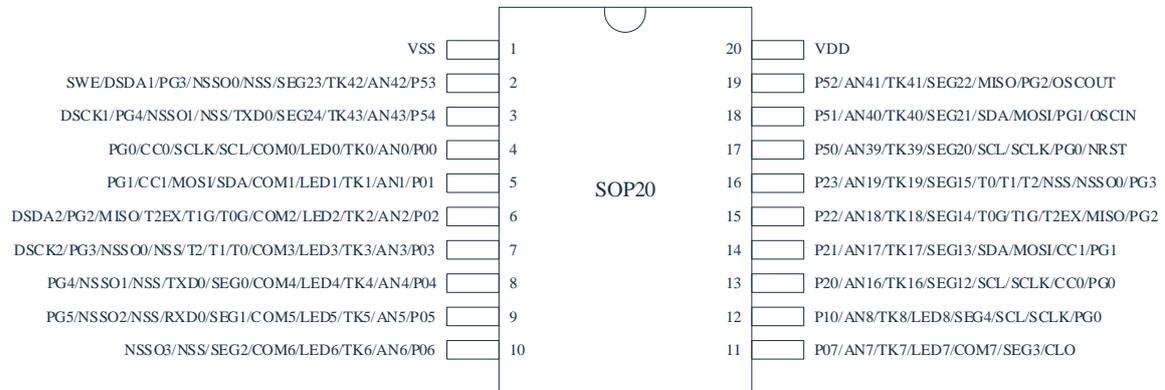
XSFR is a special register shared between the addressing space and XRAM, primarily including port control registers and other functional control registers. Its addressing range is as follows:



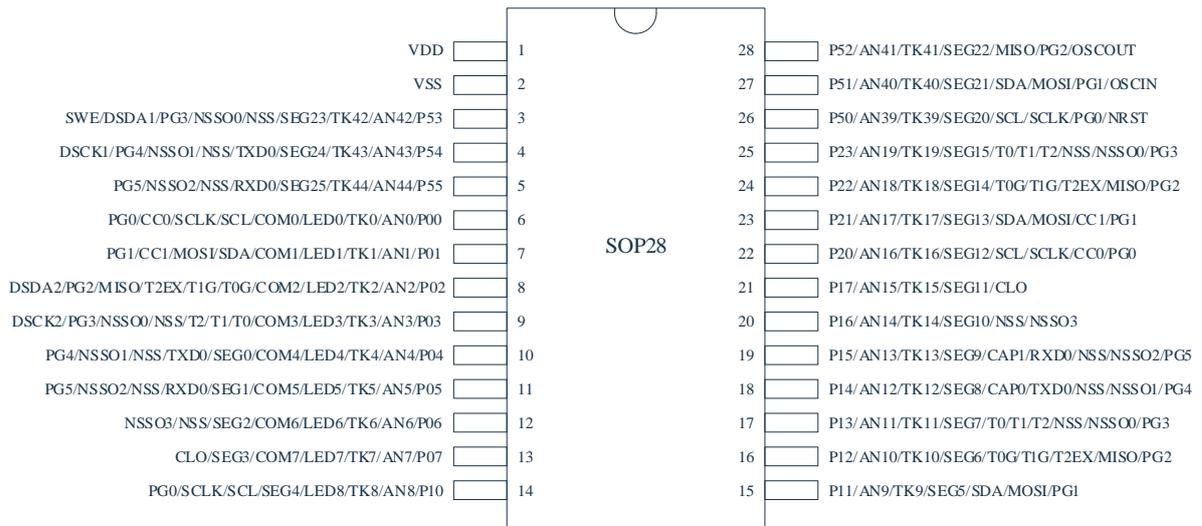
## 3. Pin Definition

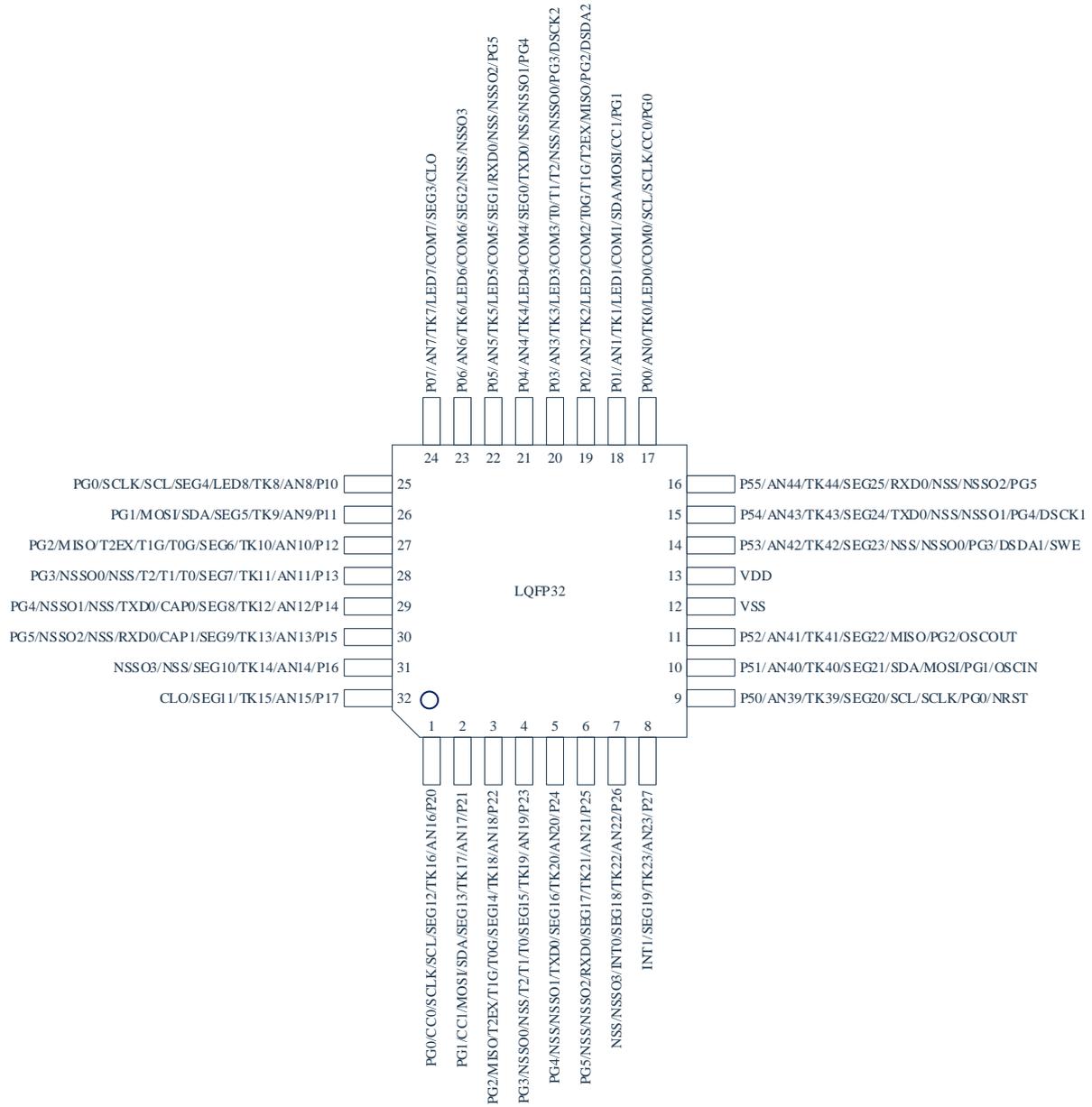
### 3.1 Top View

#### 3.1.1 CMS80F7526



#### 3.1.2 CMS80F7528



**3.1.3 CMS80F7529**


## 3.2 Pin Description

Symbol Explanation: I/O represents digital input/output, I represents digital input, O represents digital output, AI represents analog input, and AO represents analog output.

Pin number			Pin name	Pin type	Description
SOP20	SOP28	LQFP32			
4	6	17	P00	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN0	AI	ADC channel 0 input
			TK0	AI	Touch key channel 0 input
			COM0	O	LED COM0 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			SCL	I/O	I <sup>2</sup> C clock input/output
			SCLK	I/O	SPI clock input/output
			CC0	O	Timer2 compare output channel 0
			PG0	O	PWM channel 0 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
5	7	18	P01	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN1	AI	ADC channel 1 input
			TK1	AI	Touch key channel 1 input
			COM1	O	LED COM1 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			SDA	I/O	I <sup>2</sup> C data input/output
			MOSI	I/O	SPI data master transmission/slave reception
			CC1	O	Timer2 compare output channel 1
			PG1	O	PWM channel 1 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
6	8	19	P02	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN2	AI	ADC channel 2 input
			TK2	AI	Touch key channel 2 input
			COM2	O	LED COM2 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			T0G	I	Timer0 gate input
			T1G	I	Timer1 gate input
			T2EX	I	Timer2 falling edge auto-reload input
			MISO	I/O	SPI data master reception/slave transmission

Pin number			Pin name	Pin type	Description
SOP20	SOP28	LQFP32			
			PG2	O	PWM channel 2 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
			DSDA2	I/O	Programming data input/output
7	9	20	P03	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN3	AI	ADC channel 3 input
			TK3	AI	Touch key channel 3 input
			COM3	O	LED COM3 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			T0	I	Timer0 external clock input
			T1	I	Timer1 external clock input
			T2	I	Timer2 external event or gate input
			NSS0	I/O	SPI slave chip select input/master chip select 0 output
			PG3	O	PWM channel 3 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
			DSCCK2	I/O	Programming clock input
8	10	21	P04	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN4	AI	ADC channel 4 input
			TK4	AI	Touch key 4 channel
			SEG0	O	LED SEG0 output
			COM4	O	LED COM4 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			TXD0	O	UART0 data output
			RXD0	I	UART0 data input
			NSS1	I/O	SPI slave chip select input/master chip select 1 output
			PG4	O	PWM channel 4 output
			TXD1	O	UART1 data output
RXD1	I	UART1 data input			
9	11	22	P05	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN5	AI	ADC channel 5 input
			TK5	AI	Touch key 5 channel
			SEG1	O	LED SEG1 output
			COM5	O	LED COM5 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
EINT3	I	External interrupt group EINT3 input			

Pin number			Pin name	Pin type	Description
SOP20	SOP28	LQFP32			
			RXD0	I	UART0 data input
			TXD0	I	UART0 data output
			NSS2	I/O	SPI slave chip select input/master chip select 2 output
			PG5	O	PWM channel 5 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
10	12	23	P06	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN6	AI	ADC channel 6 input
			TK6	AI	Touch key 6 channel
			SEG2	O	LED SEG2 output
			COM6	O	LED COM6 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			NSS3	I/O	SPI slave chip select input/master chip select 3 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
11	13	24	P07	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN7	AI	ADC channel 7 input
			TK7	AI	Touch key 7 channel
			SEG3	O	LED SEG3 output
			COM7	O	LED COM7 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			CLO	O	System clock divider output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
12	14	25	P10	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN8	AI	ADC channel 8 input
			TK8	AI	Touch key 8 channel
			SEG4	O	LED SEG4 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			SCL	I/O	I <sup>2</sup> C clock input/output
			SCLK	I/O	SPI clock input/output
			PG0	O	PWM channel 0 output
			TXD1	O	UART1 data output
RXD1	I	UART1 data input			
-	15	26	P11	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.

Pin number			Pin name	Pin type	Description
SOP20	SOP28	LQFP32			
			AN9	AI	ADC channel 9 input
			TK9	AI	Touch key 9 channel
			SEG5	O	LED SEG5 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			SDA	I/O	I <sup>2</sup> C data input/output
			MOSI	I/O	SPI data master transmission/slave reception
			PG1	O	PWM channel 1 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
	16	27	P12	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN10	AI	ADC channel 10 input
			TK10	AI	Touch key 10 channel
			SEG6	O	LED SEG6 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			T0G	I	Timer0 gate input
			T1G	I	Timer1 gate input
			T2EX	I	Timer2 falling edge auto-reload input
			MISO	I/O	SPI data master reception/slave transmission
			PG2	O	PWM channel 2 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
	17	28	P13	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN11	AI	ADC channel 11 input
			TK11	AI	Touch key 11 channel
			SEG7	O	LED SEG7 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			T0	I	Timer0 external clock input
			T1	I	Timer1 external clock input
			T2	I	Timer2 external event or gate input
			NSS0	I/O	SPI slave chip select input/master chip select 0 output
			PG3	O	PWM channel 3 output
			TXD1	O	UART1 data output
RXD1	I	UART1 data input			
	18	29	P14	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN12	AI	ADC channel 12 input

Pin number			Pin name	Pin type	Description
SOP20	SOP28	LQFP32			
			TK12	AI	Touch key 12 channel
			SEG8	O	LED SEG8 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			CAP0	I	Timer2 input capture channel 0
			TXD0	O	UART0 data output
			RXD0	I	UART0 data input
			NSS1	I/O	SPI slave chip select input/master chip select 1 output
			PG4	O	PWM channel 4 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
	19	30	P15	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN13	AI	ADC channel 13 input
			TK13	AI	Touch key 13 channel
			SEG9	O	LED SEG9 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			CAP1	I	Timer2 input capture channel 1
			RXD0	I	UART0 data input
			TXD0	O	UART0 data output
			NSS2	I/O	SPI slave chip select input/master chip select 2 output
			PG5	O	PWM channel 5 output
TXD1	O	UART1 data output			
RXD1	I	UART1 data input			
	20	31	P16	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN14	AI	ADC channel 14 input
			TK14	AI	Touch key 14 channel
			SEG10	O	LED SEG10 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			NSS3	I/O	SPI slave chip select input/master chip select 3 output
			TXD1	O	UART1 data output
RXD1	I	UART1 data input			
	21	32	P17	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN15	AI	ADC channel 15 input
			TK15	AI	Touch key 15 channel
			SEG11	O	LED SEG11 output
			EINT0	I	External interrupt group EINT0 input

Pin number			Pin name	Pin type	Description
SOP20	SOP28	LQFP32			
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			CLO	O	System clock divider output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
13	22	1	P20	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN16	AI	ADC channel 16 input
			TK16	AI	Touch key 16 channel
			SEG12	O	LED SEG12 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			SCL	I/O	I <sup>2</sup> C clock input/output
			SCLK	I/O	SPI clock input/output
			CC0	O	Timer2 compare output channel 0
			PG0	O	PWM channel 0 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
14	23	2	P21	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN17	AI	ADC channel 17 input
			TK17	AI	Touch key 17 channel
			SEG13	O	LED SEG13 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			SDA	I/O	I <sup>2</sup> C data input/output
			MOSI	I/O	SPI data master transmission/slave reception
			CC1	O	Timer2 compare output channel 1
			PG1	O	PWM channel 1 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
15	24	3	P22	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN18	AI	ADC channel 18 input
			TK18	AI	Touch key 18 channel
			SEG14	O	LED SEG14 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			T0G	I	Timer0 gate input
			T1G	I	Timer1 gate input

Pin number			Pin name	Pin type	Description
SOP20	SOP28	LQFP32			
			T2EX	I	Timer2 falling edge auto-reload input
			MISO	I/O	SPI data master reception/slave transmission
			PG2	O	PWM channel 2 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
16	25	4	P23	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN19	AI	ADC channel 19 input
			TK19	AI	Touch key 19 channel
			SEG15	O	LED SEG15 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			T0	I	Timer0 external clock input
			T1	I	Timer1 external clock input
			T2	I	Timer2 external event or gate input
			NSS0	I/O	SPI slave chip select input/master chip select 0 output
			PG3	O	PWM channel 3 output
			TXD1	O	UART1 data output
RXD1	I	UART1 data input			
-	-	5	P24	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN20	AI	ADC channel 20 input
			TK20	AI	Touch key 20 channel
			SEG16	O	LED SEG16 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			TXD0	O	UART0 data output
			RXD0	I	UART0 data input
			NSS1	I/O	SPI slave chip select input/master chip select 1 output
			PG4	O	PWM channel 4 output
TXD1	O	UART1 data output			
RXD1	I	UART1 data input			
-	-	6	P25	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN21	AI	ADC channel 21 input
			TK21	AI	Touch key 21 channel
			SEG17	O	LED SEG17 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			RXD0	I	UART0 data input
TXD0	O	UART0 data output			

Pin number			Pin name	Pin type	Description
SOP20	SOP28	LQFP32			
			NSS2	I/O	SPI slave chip select input/master chip select 2 output
			PG5	O	PWM channel 5 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
		7	P26	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN22	AI	ADC channel 22 input
			TK22	AI	Touch key 22 channel
			SEG18	O	LED SEG18 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			INT0	I	External interrupt 0 input
			NSS3	I/O	SPI slave chip select input/master chip select 3 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
		8	P27	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN23	AI	ADC channel 23 input
			TK23	AI	Touch key 23 channel
			SEG19	O	LED SEG19 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			INT1	I	External interrupt 1 input
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
			17	26	9
AN39	AI	ADC channel 39 input			
TK39	AI	Touch key 39 channel			
SEG20	O	LED SEG20 output			
EINT0	I	External interrupt group EINT0 input			
EINT1	I	External interrupt group EINT1 input			
EINT2	I	External interrupt group EINT2 input			
EINT3	I	External interrupt group EINT3 input			
NRST	I	External reset input			
SCL	I/O	I <sup>2</sup> C clock input/output			
SCLK	I/O	SPI clock input/output			
PG0	O	PWM channel 0 output			
TXD1	O	UART1 data output			
RXD1	I	UART1 data input			
18	27	10	P51	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN40	AI	ADC channel 40 input
			TK40	AI	Touch key 40 channel

Pin number			Pin name	Pin type	Description
SOP20	SOP28	LQFP32			
			SEG21	O	LED SEG21 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			OSCIN	AI	External oscillation HSE input
			SDA	I/O	I <sup>2</sup> C data input/output
			MOSI	I/O	SPI data master transmission/slave reception
			PG1	O	PWM channel 1 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
19	28	11	P52	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN41	AI	ADC channel 41 input
			TK41	AI	Touch key 41 channel
			SEG22	O	LED SEG22 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			OSCOU	AO	External oscillation HSE output
			MISO	I/O	SPI data master reception/slave transmission
			PG2	O	PWM channel 2 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
2	3	14	P53	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN42	AI	ADC channel 42 input
			TK42	AI	Touch key 42 channel
			SEG23	O	LED SEG23 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			DSDA1	I/O	Programming/debugging data input/output
			SWE	I/O	Programming/debugging data and clock input/output
			NSS0	I/O	SPI slave chip select input/master chip select 0 output
			PG3	O	PWM channel 3 output
			TXD1	O	UART1 data output
RXD1	I	UART1 data input			
3	4	15	P54	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN43	AI	ADC channel 43 input
			TK43	AI	Touch key 43 channel
			SEG24	O	LED SEG24 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input

Pin number			Pin name	Pin type	Description
SOP20	SOP28	LQFP32			
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			DSCK1	I	Programming/debugging clock input
			TXD0	O	UART0 data output
			RXD0	I	UART0 data input
			NSS1	I/O	SPI slave chip select input/master chip select 1 output
			PG4	O	PWM channel 4 output
			TXD1	O	UART1 data output
			RXD1	I	UART1 data input
-	5	16	P55	I/O	GPIO is configured for input, output, pull-up, pull-down, and other functions through registers.
			AN44	AI	ADC channel 44 input
			TK44	AI	Touch key 44 channel
			SEG25	O	LED SEG25 output
			EINT0	I	External interrupt group EINT0 input
			EINT1	I	External interrupt group EINT1 input
			EINT2	I	External interrupt group EINT2 input
			EINT3	I	External interrupt group EINT3 input
			RXD0	I	UART0 data input
			TXD0	O	UART0 data output
			NSS2	I/O	SPI slave chip select input/master chip select 2 output
			PG5	O	PWM channel 5 output
			TXD1	O	UART1 data output
RXD1	I	UART1 data input			
20	1	13	Power supply	P	Supply voltage input pin
1	2	12	Power supply	P	Ground pin

Note: The debugging pins are DSDA1 (P53), DSCK1 (P54), or SWE (P53).

### 3.3 GPIO Features

The pins have multiple functions shared, and each I/O pin can be flexibly configured for digital or specified analog functions. As a GPIO, the I/O has the following features:

- The data latch status or pin status can be read.
- The external interrupt group can be configured to trigger interrupts on rising edge, falling edge, or both edges.
- The external interrupt group can be configured to wake up the chip on rising edge, falling edge, or both edge interrupts.
- It can be configured as a normal input, pull-up input, pull-down input, push-pull output, or open-drain output mode.

### 3.4 Pin Function List

Digital function port list:

	External input	Digital function configuration						
		0	1	2	3	4	5	6
P00	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	SCL	SCLK	CC0	PG0	TXD1/RXD1
P01	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	SDA	MOSI	CC1	PG1	TXD1/RXD1
P02	T0G/T1G/T2EX EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	MISO	-	PG2	TXD1/RXD1
P03	T0/T1/T2 EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	NSS0	-	PG3	TXD1/RXD1
P04	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	TXD0/ RXD0	NSS1	-	PG4	TXD1/RXD1
P05	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	TXD0/ RXD0	NSS2	-	PG5	TXD1/RXD1
P06	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	NSS3	-	-	TXD1/RXD1
P07	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	-	CLO	-	TXD1/RXD1
P10	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	SCL	SCLK	CLO	PG0	TXD1/RXD1
P11	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	SDA	MOSI	-	PG1	TXD1/RXD1
P12	T0G/T1G/T2EX EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	MISO	-	PG2	TXD1/RXD1
P13	T0/T1/T2 EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	NSS0	-	PG3	TXD1/RXD1
P14	CAP0 EINT0/EINT1/EINT2/EINT3	GPIO	ANA	TXD0/ RXD0	NSS1	-	PG4	TXD1/RXD1
P15	CAP1 EINT0/EINT1/EINT2/EINT3	GPIO	ANA	TXD0/ RXD0	NSS2	-	PG5	TXD1/RXD1
P16	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	NSS3	-	-	TXD1/RXD1
P17	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	-	CLO	-	TXD1/RXD1
P20	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	SCL	SCLK	CC0	PG0	TXD1/RXD1
P21	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	SDA	MOSI	CC1	PG1	TXD1/RXD1
P22	T0G/T1G/T2EX EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	MISO	-	PG2	TXD1/RXD1
P23	T0/T1/T2 EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	NSS0	-	PG3	TXD1/RXD1
P24	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	TXD0/ RXD0	NSS1	-	PG4	TXD1/RXD1
P25	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	TXD0/ RXD0	NSS2	-	PG5	TXD1/RXD1
P26	INT0 EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	NSS3	-	-	TXD1/RXD1
P27	INT1 EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	-	-	-	TXD1/RXD1
P50	NSRT EINT0/EINT1/EINT2/EINT3	GPIO	ANA	SCL	SCLK	-	PG0	TXD1/RXD1
P51	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	SDA	MOSI	-	PG1	TXD1/RXD1
P52	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	MISO	-	PG2	TXD1/RXD1
P53	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	-	NSS0	-	PG3	TXD1/RXD1
P54	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	TXD0/ RXD0	NSS1	-	PG4	TXD1/RXD1
P55	EINT0/EINT1/EINT2/EINT3	GPIO	ANA	TXD0/ RXD0	NSS2	-	PG5	TXD1/RXD1

List of LED ports, analog ports, CONFIG ports:

	GPIO(0)			ANA(1)		CONFIG
	LEDSEG	LEDCOM	LED dot matrix	ADC	TOUCH	
P00	-	COM0	LED0	AN0	TK0	-
P01	-	COM1	LED1	AN1	TK1	-
P02	-	COM2	LED2	AN2	TK2	DSDA2
P03	-	COM3	LED3	AN3	TK3	DSCCK2
P04	SEG0	COM4	LED4	AN4	TK4	-
P05	SEG1	COM5	LED5	AN5	TK5	-
P06	SEG2	COM6	LED6	AN6	TK6	-
P07	SEG3	COM7	LED7	AN7	TK7	-
P10	SEG4	-	LED8	AN8	TK8	-
P11	SEG5	-	-	AN9	TK9	-
P12	SEG6	-	-	AN10	TK10	-
P13	SEG7	-	-	AN11	TK11	-
P14	SEG8	-	-	AN12	TK12	-
P15	SEG9	-	-	AN13	TK13	-
P16	SEG10	-	-	AN14	TK14	-
P17	SEG11	-	-	AN15	TK15	-
P20	SEG12	-	-	AN16	TK16	-
P21	SEG13	-	-	AN17	TK17	-
P22	SEG14	-	-	AN18	TK18	-
P23	SEG15	-	-	AN19	TK19	-
P24	SEG16	-	-	AN20	TK20	-
P25	SEG17	-	-	AN21	TK21	-
P26	SEG18	-	-	AN22	TK22	-
P27	SEG19	-	-	AN23	TK23	-
P50	SEG20	-	-	AN39	TK39	NRST
P51	SEG21	-	-	AN40	TK40	OSCIN
P52	SEG22	-	-	AN41	TK41	OSCOUT
P53	SEG23	-	-	AN42	TK42	SWE/DSDA1
P54	SEG24	-	-	AN43	TK43	DSCCK1
P55	SEG25	-	-	AN44	TK44	-

Note: The chip pins are subject to the actual chip.

## 4. Function Summary

### 4.1 System Clock

The system clock has three clock sources, which can be selected through the system configuration register or user register settings for clock source and clock division. The system clock module has the following features:

- Internal high-speed oscillator (HSI) at 48MHz.
- External high-speed oscillator (HSE) at 8MHz/16MHz.
- Internal low-speed oscillator (LSI) at 32KHz.
- The external oscillator supports the Stop Mode Clock Monitoring (SCM) function when providing the system clock.

### 4.2 Reset

The reset operation is used to initialize the internal circuits of the chip, allowing the system to start working from a defined state. The chip supports the following types of reset:

- ◆ Power-on reset
- ◆ External reset
- ◆ Voltage detection reset
- ◆ Watch dog overflow reset
- ◆ Software reset

Each of these reset conditions requires a certain response time. The system provides a comprehensive reset process to ensure the reset operation is carried out smoothly.

## 4.3 Power Management

### 4.3.1 Operating Modes

The chip has three different operating modes to accommodate different power consumption requirements for various applications:

- Normal mode: The MCU is in normal operation, and peripherals are running as usual.
- Idle mode (IDLE): The MCU is in idle mode, where the CPU stops working while the peripherals continue to operate. This mode can be awakened by any interrupt.
- Sleep mode (STOP): The MCU is in sleep mode, where both the CPU and peripherals stop working. This mode can be awakened by INT0/1 interrupt, external interrupts, or a Timer5 interrupt.

### 4.3.2 Low Voltage Reset (LVR)

When the power supply voltage drops below the set detection voltage, the system will reset.

There are 7 selectable low voltage reset thresholds: 2.5V, 2.7V, 3.0V, 3.3V, 3.7V, 4.0V, and 4.3V.

### 4.3.3 Low Voltage Detection (LVD)

The low voltage detection circuit compares the power supply voltage with a set threshold voltage. If the power supply voltage falls below the set voltage, an interrupt request signal is generated.

The detection voltage range can be set from 2.5V to 4.3V, with 7 selectable levels.

## 4.4 Interrupt Control

The chip features multiple interrupt sources and interrupt vectors. Interrupts that can be configured by the user include INT0/1, Timer0/1, Timer2, Timer5, SCM, PWM, I2C, SPI, UART0/1, EINT0/1/2/3, ADC, LED, LVD, TOUCH. The actual number of interrupt sources varies by product.

The chip defines two interrupt priorities, allowing for two levels of interrupt nesting. When one interrupt is already being handled and a higher-priority interrupt request occurs, the higher-priority interrupt can preempt the current interrupt, allowing for interrupt nesting.

## 4.5 Timers

### 4.5.1 WDT

The Watch Dog Timer (WDT) is an on-chip timer that uses the system clock as its clock source. A WDT overflow will trigger a reset. The watch dog reset is a system protection feature that helps prevent the system from entering an indefinite deadlock state by resetting the system when it is in an unknown state. The WDT has the following features:

- 8 selectable overflow time intervals.
- Option to trigger a system reset on WDT overflow.

### 4.5.2 Timer0/1

Timer0 and Timer1 are similar in type and structure, both being 16-bit up-counters. Timer0 offers 4 operating modes, while Timer1 offers 3 operating modes, providing basic timing and event counting operations.

In timer mode, the timer register increments every 12 or 4 system cycles when the timer clock is enabled. In counter mode, the timer register increments whenever a falling edge is detected on the respective input pin (T0 or T1). Timer0/1 has the following features:

- Can be used as a regular timer.
- Can be used for gate timer functions.
- Can implement external counting functions.
- Can be used for gate counting functions.
- Provides counter overflow interrupts.

### 4.5.3 Timer2

Timer2 is a 16-bit timer that can be used for various digital signal generation and event capture, such as pulse generation, pulse-width modulation (PWM), and pulse width measurement. Timer2 has the following features:

- Can be used as a regular timer.
- Can be used for gate timer functions.
- Can implement external counting functions.
- Has reload disable, auto-reload on overflow, and auto-reload on external pin falling edge.
- Can trigger capture on rising edge, falling edge, both edges, or when writing to the lower byte of the capture register.
- Has a compare function, which can generate periodic signals and PWM waveforms with controllable duty cycles.
- Timer, external trigger, capture, and compare all can generate interrupts.

#### 4.5.4 Timer5

Timer5 is a 16-bit timer, which, when using the LSI clock source, can be used to wake up the system from sleep mode. Timer5 has the following features:

- Timer function.
- Can set a 16-bit timer value.
- Can operate normally in sleep mode.
- Can generate an interrupt when the count value equals the timer value.
- Timer interrupt can wake up the system from idle or sleep mode.
- The counting clock can be selected from 1, 2, 4, 8, 16, 32, 64, or 128 prescalers.
- Clock source can be selected as LSI or Fsys.

#### 4.5.5 Baud Rate Timer (BRT)

The BRT is a 10-bit baud rate timer, with its clock source coming from the system clock, mainly providing the clock for the UART module. BRT has the following features:

- Has an independent control switch.
- 10-bit incrementing count.

## 4.6 Enhanced Digital Peripherals

### 4.6.1 Cyclic Redundancy Check (CRC) Unit

Cyclic Redundancy Check (CRC) is one of the most commonly used error-checking codes in the field of data communication. Its feature is that the lengths of both the information field and the check field can be chosen arbitrarily. The chip's CRC check unit uses the polynomial " $X^{16}+X^{12}+X^5+1$ " (CRC16-CCITT). Through programming, the data to be checked can be specified, making this module applicable not only to the code flash area but also for multi-purpose checks.

### 4.6.2 Enhanced PWM Module

The enhanced PWM module supports 6 PWM generators, where the period and duty cycle can be set independently. PWM features the following:

- Supports two waveform output modes: one-shot and continuous.
- Supports four control modes: independent, complementary, synchronized, and group control.
- The counting clock can be divided by factors of 1, 2, 4, 8, 16, 32, 64, or 128.
- Supports edge-alignment.
- Supports dead-time programming.
- Output polarity can be set.
- Supports down-count comparison and zero-crossing interrupt.

## 4.7 Display Interfaces

### 4.7.1 Hardware LED Dot Matrix Driver Module

The LED dot matrix driver module facilitates the driving of LED dot matrix displays. This module has the following features:

- Fixed clock source.
- Supports cyclic scanning and interrupt scanning.
- Supports selectable data display for each LED.
- Supports two selectable conduction times for each LED.
- Supports up to 64 LED driving with configurable matrix options: 4x4, 5x5, 6x6, 6x7, 7x7, 7x8, 8x8.

### 4.7.2 Hardware LED Matrix Driver Module

The LED matrix driver module facilitates the driving of LED matrix displays. This module has the following features:

- Four duty cycles available: 1/4, 1/5, 1/6, and 1/8.
- Fixed clock source.
- Supports both common cathode and common anode driving modes for the COM port.
- Supports up to 8 COM ports and 26 SEG ports.
- Each COM/SEG port has an enable control bit.
- COM port current options: 55mA and 220mA.
- SEG port current options with 16 levels, maximum current up to 50mA.
- Supports dimming mode with selectable dimming time.

## 4.8 Communication Modules

### 4.8.1 SPI Module

SPI (Serial Peripheral Interface) is a fully configurable SPI master/slave device that allows users to configure the polarity and phase of the serial clock signal. SPI enables MCU communication with serial peripheral devices and also allows processor-to-processor communication in a multi-master system. The SPI module has the following features:

- Full-duplex synchronous serial data transfer.
- Supports master/slave mode.
- Supports multi-master systems.
- System error detection.
- Supports speeds up to 1/4 of the system clock ( $F_{SYS} \leq 24\text{MHz}$ ).
- Bit rates derived from system clock at 1/4, 1/8, 1/16, 1/32, 1/64, 1/128, 1/256, 1/512.
- Supports four different transfer formats.
- Interrupt generation upon completion of transmission/reception.

### 4.8.2 I<sup>2</sup>C Module

The I<sup>2</sup>C two-wire bidirectional serial bus controller provides a simple and efficient connection for data exchange between microprocessors and the I<sup>2</sup>C bus. The I<sup>2</sup>C module has the following features:

- Supports master/slave mode.
- Bidirectional data transfer between master and slave.
- Performs arbitration and clock synchronization.
- Supports multi-master systems.
- Arbitration for simultaneous data transfer between multiple masters, avoiding serial data corruption on the bus.
- The bus uses serial synchronized clock, enabling devices to transmit at different rates.
- Programmable clock for multiple rate control.
- Supports 7-bit/10-bit slave address modes.

### 4.8.3 UARTn Module

The UARTn module includes two serial ports, UART0 and UART1, which have identical functions. The UARTn module has the following features:

- Full-duplex serial port.
- Supports variable baud rate in 8-bit asynchronous transmit/receive mode.
- Supports variable baud rate in 9-bit asynchronous transmit/receive mode.
- Baud rate can be generated by Timer1/BRT module.
- Interrupt generation upon completion of transmission/reception.

## 4.9 Analog Modules

### 4.9.1 Analog-to-Digital Converter (ADC)

The ADC module is a 12-bit successive approximation analog-to-digital converter. The analog input signal from the port is routed through a multiplexer before being connected to the input of the ADC. The ADC generates a 12-bit binary result based on the input analog signal and stores the result in the ADC result register. The ADC has the following features:

- Supports up to 30 external channels.
- The ADC conversion clock has 8 selectable clock frequencies.
- The ADC reference voltage can be selected as VDD/2.4V.
- A complete 12-bit conversion requires 18.5 ADC conversion cycles.
- Supports generating an interrupt upon ADC conversion completion.

### 4.9.2 Touch Module (TOUCH)

The touch module is an integrated circuit designed for implementing human touch interfaces, replacing mechanical touch buttons. It provides a waterproof, dustproof, sealed, rugged and aesthetically pleasing operating interface.

Technical Parameters:

- Supports up to 30 selectable touch buttons.
- No external touch capacitor is required.

## 4.10 Flash Memory

The FLASH memory includes program memory (APROM) and non-volatile data memory (Data FLASH). Access operations to these memories are performed through the related special function registers (SFR) to enable In-Application Programming (IAP). The FLASH memory supports the following operations:

- Byte read operation.
- Byte write operation.
- Page erase operation.
- FLASH space CRC operation.

## 4.11 Unique ID (UID)

Each chip has a unique 128-bit identification number, known as the Unique ID (UID). It is set at the factory and cannot be modified by the user.

The address of the UID is located from 0x680 to 0x68F, corresponding to 16 bytes.

## 5. User Configuration

The System Configuration Register (CONFIG) is a FLASH option for the MCU's initial conditions, and the program cannot access or modify it. The following settings can be configured through the system configuration register:

- Watch dog operation mode.
- FLASH program area partition protection, code encryption, FLASH data area encryption status.
- Low-voltage reset voltage.
- Debug mode enable or disable.
- Oscillation mode and prescaler selection.
- Internal high-speed oscillator prescaler selection.
- External reset configuration and port selection.
- Sleep wake-up wait time.

## 6. Electrical Characteristics

Unless otherwise specified, the temperature condition for the following parameters is  $T_A = 25^\circ\text{C}$ .

### 6.1 Absolute Maximum Ratings

Symbol	Parameter	Min.	Max.	Unit
$T_{ST}$	Storage temperature	-55	150	$^\circ\text{C}$
$T_A$	Operating temperature	-40	105	$^\circ\text{C}$
VDD-VSS	Supply voltage	-0.3	5.8	V
$V_{IN}$	Input voltage	VSS-0.3	VDD+0.3	V
$I_{DD}$	VDD maximum input current	-	250	mA
$I_{SS}$	VSS maximum output current	-	300	mA
$I_{IO}$	Single IO maximum sink current	-	55	mA
	Single IO maximum sink current (LED_COM)	-	220	mA
	Single IO maximum source current	-	50	mA
	Single IO maximum source current (LED_SEG)	-	50	mA
	All IO maximum sink current	-	250	mA
	All IO maximum source current	-	200	mA

Note: If the operating conditions of the device exceed the range of **Absolute Maximum Ratings**, it will cause permanent damage to the device. The functionality can be guaranteed only when the device works within the scope specified in the manual. Operating the chip under absolute maximum rating conditions may affect the device's reliability.

## 6.2 DC Electrical Characteristics

 VDD-VSS=2.5~5.5V, T<sub>A</sub>=25°C

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
VDD	Operating voltage	F <sub>SYs</sub> =48MHz, machine cycle=2T	2.5	-	5.5	V
		F <sub>SYs</sub> =8MHz~24MHz, machine cycle=1T				
		Touch module operating voltage range	3.5	-	5.5	V
I <sub>DD</sub>	Normal mode	VDD=5V, F <sub>SYs</sub> =48MHz, all peripherals OFF F <sub>CPu</sub> =F <sub>SYs</sub> /2	-	8	-	mA
		VDD=3V, F <sub>SYs</sub> =48MHz, all peripherals OFF F <sub>CPu</sub> =F <sub>SYs</sub> /2	-	8	-	mA
		VDD=5V, F <sub>SYs</sub> =24MHz, all peripherals OFF F <sub>CPu</sub> =F <sub>SYs</sub>	-	5	-	mA
		VDD=3V, F <sub>SYs</sub> =24MHz, all peripherals OFF F <sub>CPu</sub> =F <sub>SYs</sub>	-	5	-	mA
		VDD=5V, F <sub>SYs</sub> =16MHz, all peripherals OFF F <sub>CPu</sub> =F <sub>SYs</sub>	-	4	-	mA
		VDD=3V, F <sub>SYs</sub> =16MHz, all peripherals OFF F <sub>CPu</sub> =F <sub>SYs</sub>	-	4	-	mA
		VDD=5V, F <sub>SYs</sub> =8MHz, all peripherals OFF F <sub>CPu</sub> =F <sub>SYs</sub>	-	3	-	mA
		VDD=3V, F <sub>SYs</sub> =8MHz, all peripherals OFF F <sub>CPu</sub> =F <sub>SYs</sub>	-	3	-	mA
	IDLE mode	VDD=5V, F <sub>SYs</sub> =48MHz, all peripherals OFF	-	7	-	mA
		VDD=3V, F <sub>SYs</sub> =48MHz, all peripherals OFF	-	7	-	mA
		VDD=5V, F <sub>SYs</sub> =24MHz, all peripherals OFF	-	4	-	mA
		VDD=3V, F <sub>SYs</sub> =24MHz, all peripherals OFF	-	4	-	mA
		VDD=5V, F <sub>SYs</sub> =16MHz, all peripherals OFF	-	3.5	-	mA
		VDD=3V, F <sub>SYs</sub> =16MHz, all peripherals OFF	-	3.5	-	mA
ISLEEP1	Sleep current	VDD=3V, all peripherals OFF, LSI, Timer5 enabled	-	7	-	uA
		VDD=3V, all peripherals OFF	-	6	-	uA
I <sub>LI</sub>	Input leakage	-	-1	-	1	uA
V <sub>IL</sub>	Input voltage, low	-	VSS	-	0.3VDD	V
V <sub>IH</sub>	Input voltage, high	-	0.7VDD	-	VDD	V
V <sub>OL</sub>	Output voltage, low	VDD=5V, I <sub>OL1</sub> =58.9mA	-	-	1.5	V
		VDD=5V, I <sub>OL2</sub> =225mA (LED COM)	-	-	1.5	V
		VDD=3V, I <sub>OL1</sub> =26mA	-	-	0.9	V
		VDD=3V, I <sub>OL2</sub> =100mA (LED COM)	-	-	0.9	V
V <sub>OH</sub>	Output voltage, high	VDD=5V, I <sub>OH1</sub> =54.8mA	3.5	-	-	V
		VDD=5V, I <sub>OH2</sub> =54.2mA (LED SEG Max)	3.5	-	-	V
		VDD=5V, I <sub>OH3</sub> =6.3mA (LED SEG Min)	3.5	-	-	V
		VDD=3V, I <sub>OH1</sub> =23.9mA	2.1	-	-	V
		VDD=3V, I <sub>OH2</sub> =23.7mA (LED SEG Max)	2.1	-	-	V
		VDD=3V, I <sub>OH3</sub> =2.6mA (LED SEG Min)	2.1	-	-	V
R <sub>PH</sub>	Pull-up resistor	-	-	30	-	KΩ
R <sub>PL</sub>	Pull-down resistor	-	-	30	-	KΩ

## 6.3 AC Electrical Parameters

### 6.3.1 Power-on/Power-off Operation

 $T_A=25^{\circ}\text{C}$ 

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$T_{\text{RESET}}$	Reset time	VDD=5V	-	22	-	ms
TVDDR	VDD rise rate	VDD=5V	20	-	-	us/V
TVDDF	VDD fall rate	VDD=5V	20	-	-	us/V

Remark: This specification is guaranteed by the design, and is not tested in mass production.

### 6.3.2 External Oscillator

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$V_{\text{HSE}}$	Operating voltage	F=8/16MHz, $C_{\text{XT}}=5\text{-}20\text{pF}$	2.5	-	5.5	V

### 6.3.3 Internal Oscillator

 $V_{\text{DD}}=2.5\text{V}\text{-}5.5\text{V}$ 

Symbol	Parameter	Test condition	Frequency error	Min.	Typ.	Max.	Unit
$F_{\text{HSI}}$	Internal high-speed 48MHz	$T_A=25^{\circ}\text{C}$	$\pm 1\%$		48		MHz
		$T_A=-20^{\circ}\text{C}$ to $85^{\circ}\text{C}$	$\pm 2\%$		48		MHz
		$T_A=-40^{\circ}\text{C}$ to $105^{\circ}\text{C}$	$\pm 3\%$		48		MHz
$F_{\text{LSI}}$	Internal low-speed 32KHz	$T_A=25^{\circ}\text{C}$	$\pm 20\%$	-	32	-	KHz
		$T_A=-40^{\circ}\text{C}$ to $105^{\circ}\text{C}$	$\pm 50\%$	-	32	-	KHz

Remark: Low-temperature specification values are guaranteed by the design, and are not tested in mass production.

### 6.3.4 POR Electrical Parameters

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$V_{\text{POR}}$	Low power reset detection circuit	$T_A=25^{\circ}\text{C}$		2.1		V

Remark: This specification is guaranteed by the design, and is not tested in mass production.

### 6.3.5 LVD Electrical Parameters

Symbol	Parameter	Min.	Typ.	Max.	Unit
$V_{\text{LVR1}}$	Low voltage detection threshold 2.50V	2.35	2.5	2.65	V
$V_{\text{LVR2}}$	Low voltage detection threshold 2.70V	2.55	2.7	2.85	V
$V_{\text{LVR3}}$	Low voltage detection threshold 3.00V	2.85	3.0	3.15	V
$V_{\text{LVR4}}$	Low voltage detection threshold 3.30V	3.15	3.3	3.45	V
$V_{\text{LVR5}}$	Low voltage detection threshold 3.70V	3.55	3.7	3.85	V
$V_{\text{LVR6}}$	Low voltage detection threshold 4.00V	3.85	4.0	4.15	V
$V_{\text{LVR7}}$	Low voltage detection threshold 4.30V	4.15	4.3	4.45	V

**6.3.6 LVD Electrical Parameters**

Symbol	Parameter	Min.	Typ.	Max.	Unit
V <sub>LVD1</sub>	Low voltage detection threshold 2.50V	2.35	2.5	2.65	V
V <sub>LVD2</sub>	Low voltage detection threshold 2.70V	2.55	2.7	2.85	V
V <sub>LVD3</sub>	Low voltage detection threshold 3.00V	2.85	3.0	3.15	V
V <sub>LVD4</sub>	Low voltage detection threshold 3.30V	3.15	3.3	3.45	V
V <sub>LVD5</sub>	Low voltage detection threshold 3.70V	3.55	3.7	3.85	V
V <sub>LVD6</sub>	Low voltage detection threshold 4.00V	3.85	4.0	4.15	V
V <sub>LVD7</sub>	Low voltage detection threshold 4.30V	4.15	4.3	4.45	V

## 6.4 Flash Electrical Parameters

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
V <sub>F</sub>	FLASH operating voltage	-	2.5	-	5.5	V
T <sub>F</sub>	FLASH operating temperature	-	-40	25	105	°C
N <sub>ENDURANCE</sub>	Erase cycle count <sup>Note 1</sup>	Program FLASH	20,000	-	-	Cycle
		Data FLASH	100,000	-	-	Cycle
T <sub>RET</sub>	Data retention time <sup>Note 1</sup>	25°C	100	-	-	year
T <sub>ERASE</sub>	Sector erase time	-	-	1.5	-	ms
T <sub>WRITE</sub>	Write time	-	-	30	-	us
T <sub>READ</sub>	Read time	-	-	3*T <sub>sys</sub>	-	-
I <sub>DD1</sub>	Read current	-	-	-	2.5	mA
I <sub>DD2</sub>	Programming current	-	-	-	3.6	mA
I <sub>DD3</sub>	Erase current	-	-	-	2	mA

Note 1: This specification is guaranteed by the design, and is not tested in mass production.

## 6.5 Analog Characteristics

### 6.5.1 BANDGAP Electrical Characteristics

 $T_A=25^{\circ}\text{C}$ 

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$V_{BG}$	Internal reference 0.8V	VDD=2.5~5.5V, $T_A=25^{\circ}\text{C}$	0.792	0.8	0.808	V
		VDD=2.5~5.5V, $T_A=-20^{\circ}\text{C}$ to $85^{\circ}\text{C}$	0.788	0.8	0.812	V
		VDD=2.5~5.5V, $T_A=-40^{\circ}\text{C}$ to $105^{\circ}\text{C}$	0.784	0.8	0.816	V

### 6.5.2 Internal Reference Voltage 2.4V Electrical Characteristics

 $T_A=25^{\circ}\text{C}$ 

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$V_{ADCLDO}$	2.4V	VDD=2.9~5.5V, $T_A=25^{\circ}\text{C}$	2.376	2.4	2.424	V
		VDD=2.9~5.5V, $T_A=-20^{\circ}\text{C}$ to $85^{\circ}\text{C}$	2.364	2.4	2.436	V
		VDD=2.9~5.5V, $T_A=-40^{\circ}\text{C}$ to $105^{\circ}\text{C}$	2.352	2.4	2.448	V

### 6.5.3 ADC Electrical Characteristics

 $T_A=25^{\circ}\text{C}$ 

Symbol	Parameter	Min.	Typ.	Max.	Unit	
$V_{AVDD}$	ADC operating voltage	2.5	-	5.5	V	
$V_{REF1}$	Reference voltage 1	-	$V_{AVDD}$	-	V	
$V_{REF2}$	Reference voltage 2 <sup>(Note 1)</sup>	2.385	2.4	2.415	V	
$V_{ADI}$	Input voltage	0	-	$V_{REF}$	V	
$N_R$	Resolution	12			Bit	
DNL	Differential nonlinearity error ( $V_{REF}=V_{AVDD}=5\text{V}$ , $T_{ADCK}=0.5\mu\text{s}$ )	$\pm 2$			LSB	
INL	Integral nonlinearity error ( $V_{REF}=V_{AVDD}=5\text{V}$ , $T_{ADCK}=0.5\mu\text{s}$ )	$\pm 4$			LSB	
$T_{ADCK}$	ADC clock cycle	$V_{REF}=V_{DD}=5\text{V}$	0.5	-	-	us
		$V_{REF}=V_{REF2}$	2	-	-	us
$T_{ADC}$	ADC conversion time	-	18.5	-	$T_{ADCK}$	
$F_S$	Sampling rate ( $V_{REF}=V_{AVDD}=5\text{V}$ )	100			Ksps	

Note: When  $V_{REF}=V_{REF2}$ , the precision is 8 bits.

Note 1: Test conditions:  $T_A = 25^{\circ}\text{C}$  and  $V_{AVDD} = 5.0\text{V}$ .

## 6.6 EMC Characteristics

### 6.6.1 EFT Electrical Characteristics

Symbol	Parameter	Test condition	Grade
V <sub>EFTB</sub>	Fast transient voltage burst limits to be applied through 0.1μF (capacitance) on VDD and VSS pins to induce a functional disturbance	T <sub>A</sub> = + 25°C, F <sub>sys</sub> =48MHz, conforms to IEC 61000-4-4	4B

Note: The electrical fast transient burst (EFT) immunity performance is closely related to system design (including power supply structure, circuit design, layout and wiring, chip configuration, program structure, etc.) The EFT parameters in the above table are the results measured on the internal test platform of the CMS, and are not applicable to all application environments. The test data is only for reference. All aspects of system design may affect the EFT performance. In applications with high EFT performance requirements, attention should be paid to avoid interference sources affecting the system operation as much as possible. It is recommended to analyze the interference path and optimize the design to achieve the best anti-interference performance.

### 6.6.2 ESD Electrical Characteristics

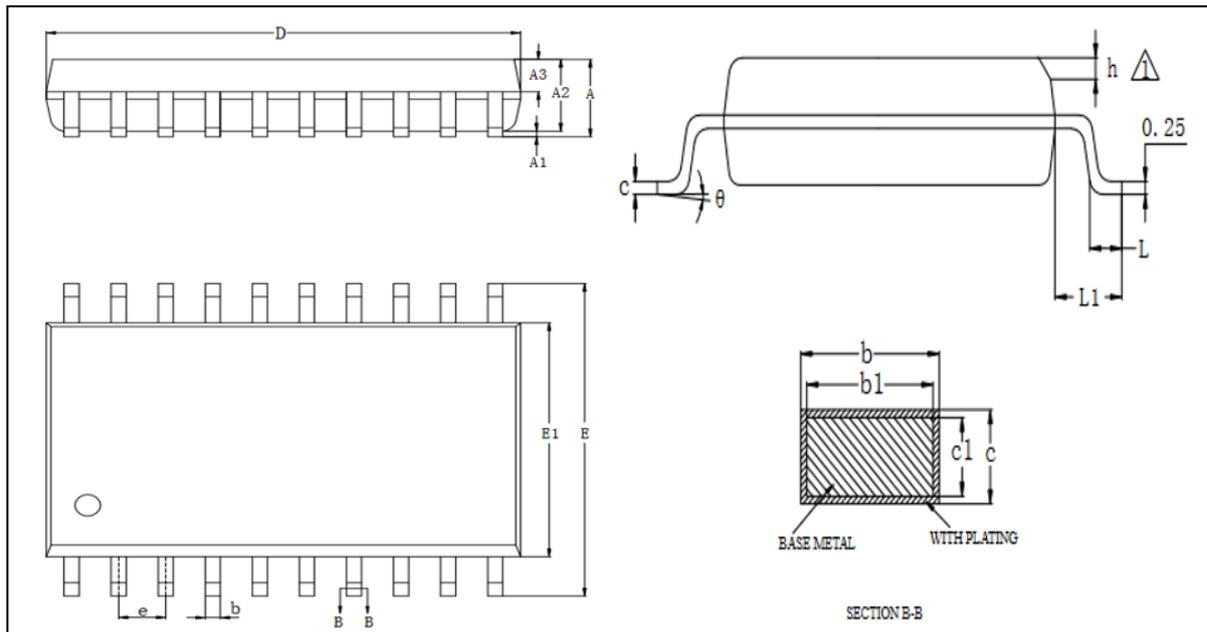
Symbol	Parameter	Test condition	Grade
V <sub>ESD</sub>	Electrostatic discharge (Human body discharge mode HBM)	T <sub>A</sub> = 25°C, ANSI/ESDA/JEDEC JS-001-2024	3A
	Electrostatic discharge (Device Charging Model CDM)	T <sub>A</sub> = 25°C, ANSI/ESDA/JEDEC JS-002-2022	C3

### 6.6.3 Latch-Up Electrical Characteristics

Symbol	Parameter	Test condition	Class
LU	Static Latch-Up	JESD78F	Class IA (T <sub>A</sub> = +25°C)

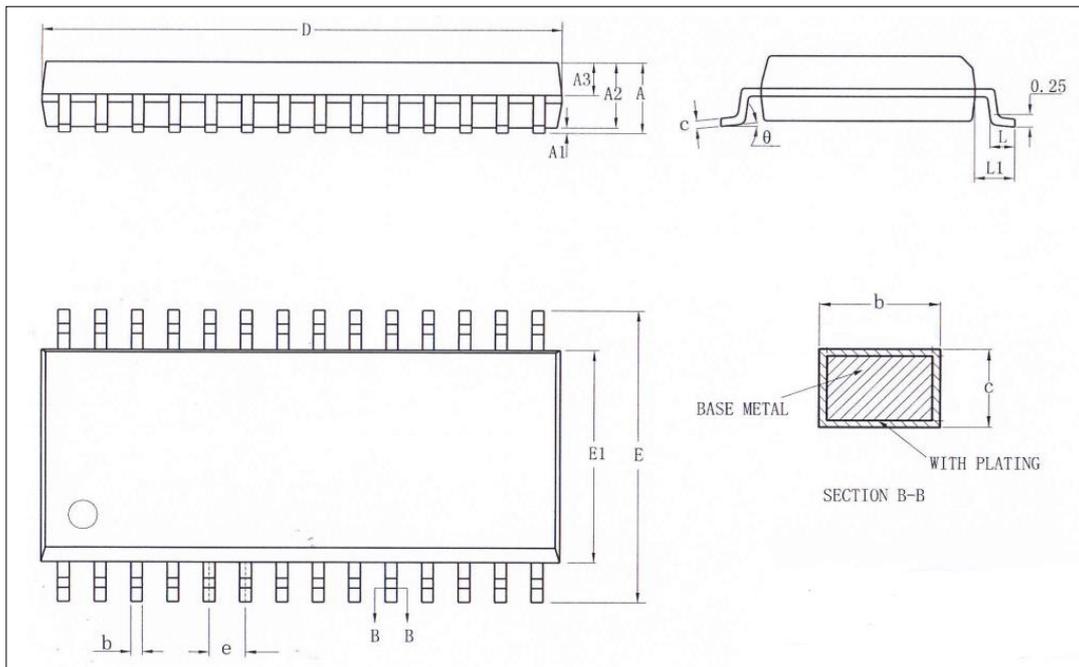
## 7. Package Dimensions

### 7.1 SOP20



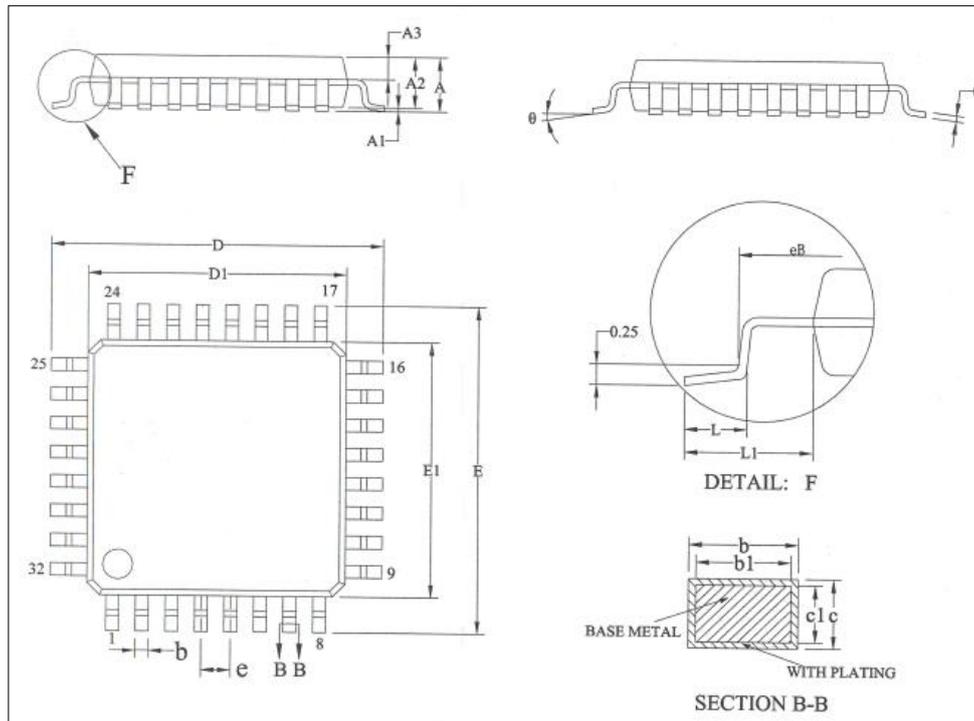
Symbol	Millimeter		
	Min	Nom	Max
A	-	-	2.65
A1	0.10	-	0.30
A2	2.24	-	2.44
A3	0.97	1.02	1.07
b	0.39	-	0.47
b1	0.38	0.41	0.44
c	0.25	-	0.30
c1	0.24	0.25	0.26
D	12.65	-	12.90
E	10.10	10.30	10.50
E1	7.40	7.50	7.60
e	1.27BSC		
h	0.50REF		
L	0.70	-	1.01
L1	1.40REF		
θ	0	-	8°

Caution: Package dimensions do not include mold flash or gate burrs.

**7.2 SOP28**


Symbol	Millimeter		
	Min	Nom	Max
A	-	-	2.65
A1	0.10	-	0.30
A2	2.24	-	2.44
A3	0.97	1.02	1.07
b	0.39	-	0.47
c	0.25	-	0.30
D	17.90	18.00	18.10
E	10.10	10.30	10.50
E1	7.40	7.50	7.60
e	1.27BSC		
L	0.70	-	1.01
L1	1.40REF		
$\theta$	0	-	8°

Caution: Package dimensions do not include mold flash or gate burrs.

**7.3 LQFP32**


Symbol	Millimeter		
	Min	Nom	Max
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
A3	0.59	0.64	0.69
b	0.32	-	0.43
b1	0.31	0.35	0.39
c	0.13	-	0.18
c1	0.12	0.13	0.14
D	8.80	9.00	9.20
D1	6.90	7.00	7.10
E	8.80	9.00	9.20
E1	6.90	7.00	7.10
eB	8.10	-	8.25
e	0.80BSC		
L	0.45	-	0.75
L1	1.00REF		
θ	0	-	7°

Caution: Package dimensions do not include mold flash or gate burrs.

## 8. Revision History

Version #	Date	Description of changes
V0.5.0	Mar. 2025	Initial release
V0.5.1	Mar. 2025	Modified DC electrical characteristics and output high/low voltage data
V0.5.2	Jul. 2025	1) Modify the description of the function introduction section 2) Updated HSE test conditions in Section 6.3.2 External Oscillator.